

# Fabrication of Cooling Jacket For Motorcycle

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**Abstract-** Due to metabolic heat generation from our body, we are very uncomfortable both in cold and hot weather, especially when we work hard and while travelling. In cold weather we wear warm jacket to have more comfort. But, we can't have much comfort when we use jacket. Unlike cold weather, in hot weather we don't have such an alternative solution for comfort. If there is a jacket cooler, then it will be comfort both in cold and hot weather. A thermoelectric cooling prototype jacket has been fabricated. An innovative evaporative type heat sink has been designed and fabricated. A control switch used to regulate the flow of current through the circuit. Thus to control the heat capacity of the module has been prepared. The performance of the prototype jacket was evaluated by analytical and numerical methods.

It works on the principle of peltier effect. The thermoelectric cell takes advantage of this effect with a thermopile--essentially a stack of different pieces of metal attached together. One end of the thermopile gets very hot and the other end gets cold. It utilizes a DC current, when the electrons pass from higher electron density material to lower electron density material, one junction of the metal becomes heated and the other is cooled. In this project we utilize the power of a motorcycle battery to charge the jacket.

## I. INTRODUCTION

Conventional cooling systems such as those used in refrigerators utilize a compressor and a working fluid to transfer heat. Heat energy is absorbed and released as the working fluid undergoes compression and expansion and changes phase from vapor to liquid to and back, respectively. Semiconductor thermoelectric cells (also known as peltier coolers) offer many advantages over conventional refrigeration.

They are totally solid state devices, with no moving parts and this makes them reliable, rugged, and quiet. They use no ozone depleting chlorofluorocarbons, potentially offering a more environmentally responsible alternative to refrigeration systems which are conventional. They are extremely compact, much more than compressor based systems. Precise temperature control ( $< \pm 0.1$  °C) can be

acquired with Peltier cells. However, their efficiency is low compared to natural conventional refrigerator.

Thus, they are used in these applications, where their unique advantages outweigh their low efficiency. Although some large scale applications have been considered (on submarines and surface vessels), Peltier cells are generally used in applications where small size is needed and the cooling demands are not too great, such as for cooling electronic components.

## COMPARISON OF THERMOELECTRIC CELL REFRIGERATION AND OTHER METHODS OF REFRIGERATION

### Thermoelectric Refrigeration System

Cooling is achieved electronically using the "Peltier effect". The heat is pumped with electrical energy. Thermoelectric cooling provides an alternative solution to the common compressor and absorber cooler. Thermoelectric coolers are used especially if small cooling power is needed (up to 100 W).

### Vapour Compression Refrigeration System:

Cooling is achieved by vaporizing a refrigerant (such as Freon) inside the refrigerator. Heat is absorbed by the refrigerant through the principle of the "latent heat of vaporization" and released outside the refrigerator where the vapour is condensed and compressed into a liquid again. This uses mechanical energy.

### Vapour Absorption Refrigeration System:

Cooling is achieved by vaporizing a refrigerant inside the refrigerator by boiling it out of a water ammonia solution with a heat source (electric or propane). This uses the principle of "latent heat of vaporization". The vapour is condensed and reabsorbed by the ammonia solution outside the refrigerator. Uses heat energy.

## THERMOELECTRIC REFRIGERATION

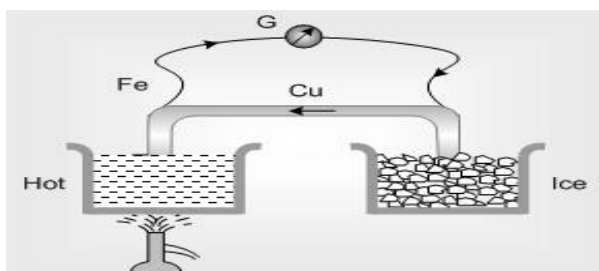
Refrigeration is the process of pumping heat energy out of an insulated chamber in order to reduce the temperature of the chamber below that of the surrounding air. Thermoelectric refrigeration uses a principle called the "PELTIER" effect to pump heat electronically. The Peltier effect is named after a French scientist who discovered it in 1834. In 1834 Jean Peltier noted that when an electrical current is applied across the junction of two dissimilar metals, heat is removed from one of the metals and transferred to the other.

This is the basis of thermoelectric refrigeration. Thermoelectric modules are constructed from a series of tiny metal cubes of dissimilar exotic metals which are physically bonded together and connected electrically. When electrical current passes through the cube junctions, heat is transferred from one metal to the other. Solid state thermoelectric modules are capable of transferring large quantities of heat when connected to a heat absorbing device on one side and a heat dissipating device on the other. The Koolatron's internal aluminum cold plate fins absorb heat from the contents, (food and beverages), and the thermoelectric modules transfer it to heat dissipating fins under the control panel. Here, a small fan helps to disperse the heat into the air. The system is totally environmentally friendly and contains no hazardous gases, nor pipes nor coils and no compressor.

The only moving part is the small 12-volt fan. Thermoelectric modules are too expensive for normal domestic and commercial applications which run only on regular household current. They are ideally suited to recreational applications because they are lightweight, compact, and insensitive to motion or tilting, have no moving parts, and can operate directly from 12-volt batteries.

## SEEBECK EFFECT

**Definition:** When the two junctions of a thermocouple are maintained at different temperatures, then a current starts flowing through the loop known as thermo electric current. The potential difference between the junctions is called thermo electric emf which is of the order of a few microvolts per degree temperature difference ( $\mu\text{V}/^\circ\text{C}$ ).



SEEBECK EFFECT

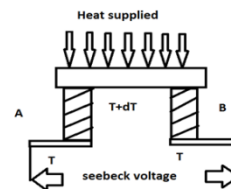
**Seebeck effect:** The magnitude and direction of thermo emf in a thermocouple depends not only on the temperature difference between the hot and cold junctions but also on the nature of metals constituting the thermocouple.

(i) Seebeck arranged different metals in the decreasing order of their electron density. Few metals forming the series are as below:

Sb, Fe, Cd, Zn, Ag, Au, Cr, Sn, Pb, Hg, Mn, Cu, Pt, Co, Ni, Bi

(ii) Thermo electric emf is directly proportional to the distance between the two metals in series. Farther the metals in the series forming the **thermocouple** greater are the thermo emf. Thus maximum thermo emf is obtained for **Sb-Bi** thermo couple.

(iii) The current flow at the hot junction of the thermocouple is from the metal occurring later in the series towards that occurring earlier. Thus, in the copper iron thermocouple the current flows from copper (Cu) to iron (Fe) at the hot junction. This may be remembered easily by the hot coffee.



Seebeck effect

SEEBECK EFFECT

- For small temperature difference between two junctions of materials A and B the open circuit voltage developed is proportional to the temperature difference and is given by
- $\Delta V = \alpha_{ab} \Delta T$

## THERMOELECTRIC MODULE

The core piece of a thermoelectric suit is the thermoelectric module. A thermoelectric module is an electrical module, which produces a temperature difference with current flow. The emergence of the temperature difference is based on the Peltier effect designated after Jean Peltier. The thermoelectric module is a heat pump and has the same function as a refrigerator. It gets along however without mechanically mobile construction units (compressor, refrigerant pump,) and without cooling fluids. The heat flow can be turned by reversal of the direction of current.

**DESIGN OF THERMOELECTRIC COMPONENTS**

The design progressed through a series of steps. These steps were identification of the problem, analyze problem, brainstorm ideas, decide upon a design selection, and implement design. Redesign if necessary. The main design considerations were Geometry, Heat Transfer Methods and Materials.

**HEAT TRANSFER METHODS**

There are several methods which can be employed to facilitate the transfer of heat from the surface of the thermoelectric to the surrounding. These methods are described in the following three sections: Natural convection, Liquid cooled, Forced convection. When the coefficient of thermal transfer ( $K$ ) was investigated, the  $K$  for natural convection was approximately 25 W/mK. This value compared to 100W/mK for forced convection. Clearly the size of the heat sink for a natural convection apparatus would need to be 4 times that for a forced convection set-up.

**GEOMETRY**

Two main geometries were considered for the device. The first choice for cooler geometry was a cylinder. The advantage found with this shape is that it has the largest volume to surface area ratio of the two designs considered. This is a good property when the objective is to minimize heat loss and the second was a rectangle. The advantage of rectangle is its simplicity to build and insulate.

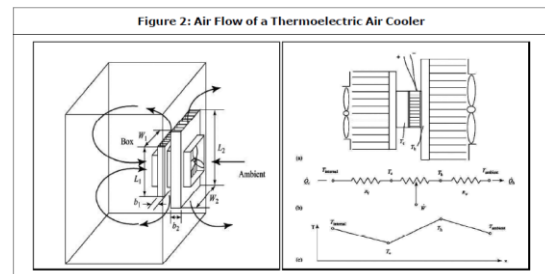
A door can easily be attached to one of the sides. Finally any insulation, thermoelectric modules or heat sinks are easily fastened to the sides. So by considering the simplicity to build and insulate rectangle box is considered.

**MATERIAL**

We explored three different materials for the construction of the outer casing and frame of the device. These were aluminum, stainless steel and Hips. High impact polystyrene is desirable as it has a low thermal conductivity. Building the device out of wood would make it very light, portable while maintaining rigidity is readily available and reasonably priced, is easy to cut and drill. The outer casing and container would be made by first making a positive mold and applying a cloth coated with resin.

**HEAT SINK DESIGN**

In order to visualize the energy flow in the entire system, a thermal circuit is constructed, which is schematically shown in Figure 2.  $R_c$  and  $R_h$  are the overall thermal resistances for the internal heat sink and external heat sink, respectively. The components of the air cooler are an internal heat sink, a thermoelectric module, and an external heat sink as shown in Figure 2. The amount of heat transported at the internal heat sink, which is actually the design requirement (45 Watts).



HEAT SINK DESIGN

FIGURE Considering the dimension available at the machine area and various options keeping the weight, cost and manufacturing feasibility as the main consideration for selection for mounting of heat sink both at hot and cold side area. Fin thickness of 1mm with profile length of 20 mm is selected. Tables 3 and 4 represent the summary result for hot side and cold side fin respectively.

**THERMOELECTRIC CELL**

Using Standard correlation available in handbooks the commercial available module with the calculated maximum performance is represented in Table below.

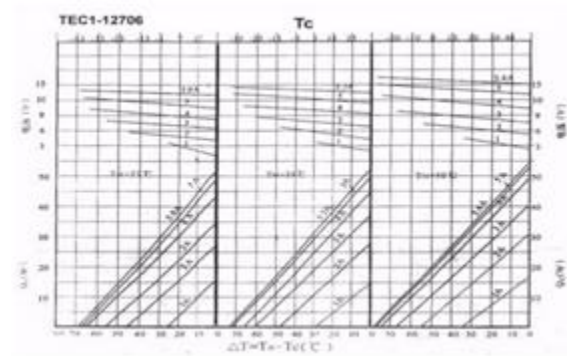
Table 5: Model Number for TER			
Module: Model TEC1-127-06L			
$Q_{max}$	51.4 Watts	Dimensions	
$I_{max}$	6 Amp	Width	40 mm
$V_{max}$	15.4 V	Length	40 mm
$T_{max}$	67 °C	Thickness	3.8 mm
Number of Thermocouple	127		

Thermoelectric Cooler’s Specification Include

Part Number	Data obtained at hot plate temperature Th=27°C.				Dimension AxBxHmm
	I <sub>max</sub> (amps)	DT <sub>max</sub> (°C)	V <sub>max</sub> (Volts)	Q <sub>max</sub> (watts)	
TEC101703	3.3	69	1.90	3.90	15x15x4.8
TEC1-03103			3.50	7.20	20x20x4.8
TEC1-07103			8.60	16.40	30x30x4.8
TEC1-12703			15.00	29.30	40x40x4.8
TEC1-01704	3.9	69	2.00	4.00	15x15x4.7
TEC1-03104			3.66	7.30	20x20x4.7
TEC1-07104			8.40	16.70	30x30x4.7
TEC1-12704			15.00	33.40	40x40x4.7
TEC1-01705	5.0	68	2.00	5.60	15x15x4.3
TEC1-03105			3.66	10.30	20x20x4.3
TEC1-07105			8.40	23.70	30x30x4.3
TEC1-12705			15.00	42.50	40x40x4.3
TEC1-01706	6.0	68	2.00	6.90	15x15x4.0
TEC1-03106			3.66	12.50	20x20x4.0
TEC1-07106			8.40	28.70	30x30x4.0
TEC1-12706			15.00	51.40	40x40x4.0
TEC1-03108	8.5	68	3.75	16.80	20x20x3.3
TEC1-07108			8.60	38.50	30x30x3.3
TEC1-12708			15	68.09	40x40x3.3
TEC1-127085			15	68.09	50x50x4.7
TEC1-12710S	10	68	15.80	85.0	40x40x3
TEC1-12710	10	68	15.80	85.0	50x50x4.8
TEC1-07114	14	68	8.40	65.90	44x44x4.6
TEC1-12714			15.80	118	50x50x4.6
TEC1-12718	18.5	68	15.8	156	50x50x4.1
TEC1-12726	26	65	15.8	220	50x50x3.6
TEC1-03140	39	65	3.63	80.0	55x55x5.8

Where

- I – Input Amps to the TEC (in Amps)
- I<sub>max</sub> – Input Amps that produce the maximum DT [DT<sub>max</sub>] (in Amps)
- Q<sub>c</sub> – Amount of heat that can be absorbed at the cold side face of the TEC (in watts)
- Q<sub>max</sub> – Maximum amount of heat that can be absorbed at the cold side This occurs at
- I = I<sub>max</sub> and when DT = 0 (in Watts)
- Th – Temperature of the hot side face of the TEC (in °C)
- T<sub>c</sub> – Temperature of the cold side face of the TEC (in °C)
- DT – Difference in temperature between the hot side (Th) and the cold side (T<sub>c</sub>)
- dT = Th-T<sub>c</sub> (in °C)
- DT<sub>max</sub> – Maximum difference in temperature a TEC can achieve between the hot side (Th) and the cold side (T<sub>c</sub>)
- This occurs at I = I<sub>max</sub> and when Q<sub>c</sub> = 0 (in °C)
- V<sub>max</sub> – Voltage at I = I<sub>max</sub> (in Volts) F



PELTIER GRAPH

## II LITERATURE REVIEW

### THERMO ELECTRIC OPERATING PRINCIPLE:

Thermoelectric coolers operate by the Peltier effect (which also goes by the more general name thermoelectric effect) The device has two sides, and when DC current flows through the device, it brings heat from one side to the other, so that one side gets cooler while the other gets hotter The "hot" side is attached to a heat sink so that it remains at ambient temperature, while the cool side goes below room temperature In some applications, multiple coolers can be cascaded together for lower temperature

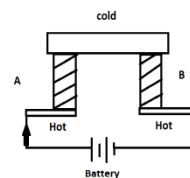
In 1834, Jean Peltier discovered that when a direct current is passed through a junction of two dissimilar metals, the junction became either hot or cold The same circuit can be considered as made up of material A and B into which a battery is introduced to provide a direct current I At the junction between the two dissimilar metals, the heat evolved or absorbed in unit time proportional to the current and is given by

$$Q_p = \pi_{ab} I$$

Q<sub>p</sub>=heat evolved or absorbed in unit time, (watts)

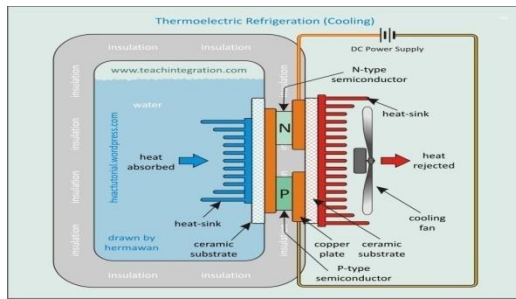
Π<sub>ab</sub>=peltier coefficient

I=direct current in amperes



Peltier effect

### PELTIER EFFECT



- In 1838, Emil Lenz clearly showed the importance of both Peltier's and Seebeck's discovery by placing a drop of water on a junction of two dissimilar metals and passing a direct current through the circuit when the current flowed in one direction, the water froze. When the flow of current reversed, the ice melted. However, Lenz, like his predecessors, failed to realize the significance of his findings and the knowledge remained dormant for over 100 years, mainly due to unavailability of materials which could produce wide temperature differences.

Before discussing the principles of thermoelectric refrigeration, it is necessary to see the required properties of the materials which meet the following conditions:

- The thermo-electric material must be an excellent conductor of electricity to minimize resistance losses.
- The thermo electric material must be a very poor conductor of heat because the heat must be absorbed at one end, and rejected at the other.
- The thermo electric material must have high thermoelectric power. This means it must have a high rate of change in voltage with temperature that means  $[dE/dT]$  must be high.
- A good thermo-electric material should have a higher electrical conductivity, low thermal conductivity, and a high Seebeck coefficient.
- After the discovery of the transistor which required semiconductors, the development of thermo electric refrigerators took the practical shape because the semiconductor was the proper material for thermoelectric refrigeration.

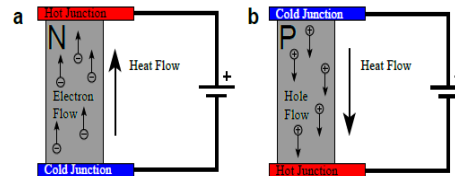
### THE PELTIER DEVICE:

Peltier devices are named so because, typically, they are used as a heat pump based on the Peltier effect. In this case, a constant current,  $I_{el}$ , is driven through the Peltier device, and the Peltier effect generates a temperature difference

$$\Delta T \propto P_{el} = \Pi I_{el}.$$

### N- AND P-TYPE PELTIER ELEMENTS:

When a semiconductor is used as a thermoelectric material, its majority charge carriers (electrons or holes) determine the electrical behavior. For example, when n-type semiconductors are biased in the same direction, their charge carriers flow in opposite directions. As a result, n-type Peltier elements create opposite temperature gradients.



N AND P PELTIER ELEMENTS

n-type versus p-type Peltier elements

- An n-type semiconductor is biased externally, creating an electrical current. The negative carriers (electrons) carry heat from bottom to top via the Peltier effect.
- The positive carriers (holes) within a p-type semiconductor, biased in the same direction as (a), pump heat in the opposite direction, that is, from top to bottom.

### COMMERCIAL PELLETIER DEVICES:

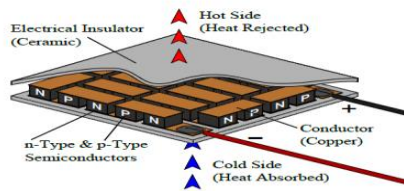
A single Pelletier element can be used to produce electrical power (via the Seebeck effect) or to pump heat (via the Peltier effect). In either application, the power output of a single Peltier element is generally not sufficient for realistic situations. To increase their power, commercial Peltier devices are composed of many n-type and p-type semiconductor Peltier elements.

The individual elements are connected in series using metallic junctions. As a result of this, the junctions between the semiconductors do not form a barrier potential, as they would do in a pn diode, and charge carriers flow freely in both directions. In a Peltier device, the individual elements are arranged so that the n- and p-type heat flow in the same direction.

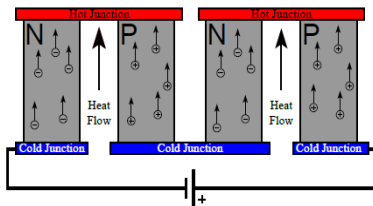
**Complete Peltier device architecture** It consists of two electrically insulating ceramic plates sandwiching a series of p pairs joined by copper. This design provides a large surface area, improving heat pumping for cooling and heating applications. Waste heat absorption and electrical power production (via the Seebeck effect) also benefit from the increased surface area.

### ELECTRICAL POWER PRODUCTION:

Though primarily used as heat pumps, Peltier devices nonetheless generate a thermovoltage,  $V_{th}$ , when subjected to a temperature gradient,  $\Delta T$ . An electrical current,  $I$  will flow if the Peltier device is connected to a load resistor,  $R_{load}$ . In this case, the Peltier device converts heat energy to electrical energy quantified by the dissipated power,  $P = IV_{load}$ , where  $V_{load}$  is the voltage drop across the load resistor. In the laboratory,  $P$  can be determined by measuring  $I$  and  $V_{load}$ . The Peltier device is not an ideal voltage source; therefore, its internal resistance,  $R_I$ , must be included in the analyses of power data. Furthermore,  $R_I$  is typically on the order of a few tens of Ohms. Therefore, the resistance of the ammeter,  $R_a$ , cannot be ignored.



A series of alternating n and p-type semiconductor elements, which pump heat from bottom to top when a voltage is applied.

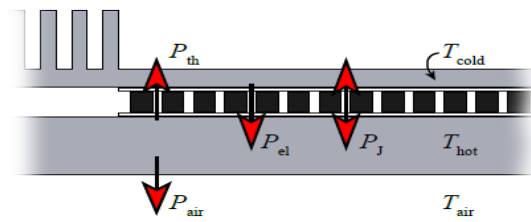


**ELECTRICAL POWER PRODUCTION**

The common design of a commercial Peltier device is placed between two ceramic insulating materials, alternating n and p-type semiconductor elements are arranged across a plane and are connected in series electrically with copper junctions. When current is supplied to the Peltier device, heat is pumped from one surface to the other.

**Thermal conductance:**

When current,  $I$ , flows through the Peltier device, heat flow  $P_{el} = \Delta I$  generates a temperature difference,  $\Delta T$ . In response, heat conducts from the hot to the cold side of the Peltier device given by  $P_{th} = \kappa \Delta T$ . The electrical power dissipated in the Peltier device (that is, the Joule heat) is  $P_J = RI^2$ , where  $R$  is the resistance of the Peltier device.  $P_J$  flows into both sides of the Peltier device. Finally, heat  $P_{air}$  flows from the hot side to the surrounding environment.



**THERMAL CONDUCTANCE**

Heat flows in the Peltier device. Current,  $I$ , owing through the Peltier device pumps heat  $P_{el} = \Delta I$  and generates the temperature gradient,

$$\Delta T = T_{hot} - T_{cold}$$

In the opposite direction as  $P_{el}$ , heat  $u_x P_{th}$  conducts through the Peltier device from hot to cold. Joule heat,  $P_J$ , flows into both sides of the Peltier device. Heat  $P_{air}$  conducts from the heat block to the surrounding air at temperature  $T_{air}$ . A number of simplifications and approximations can be made to reduce the complexity of these heat flows during measurements.

The first simplification is to perform the experiments in the open-circuit regime where  $I = 0$ . Therefore  $P_{el} = P_J = 0$ .

The approximations are to assume that  $T_{cold} \approx T_{air}$  and that  $P_{air} \approx 0$ . These assumptions are filled when  $\Delta T$  is small and when the heat block is thermally insulated. In this situation, only  $P_{th}$  affects the heat content of the hot block because  $T_{cold}$  is constant. The heat stored in the heat block is  $Q_{hot} = mcT_{hot}$ , where  $m = 0.22$  kg is the mass of the heat block, and  $c = 897$  J/(kg K) is the heat Capacity of aluminum. The rate equation for the heat flow is

$$P_{th} = \Delta Q_{hot} = mc \Delta T_{hot} = \kappa \Delta T_{hot}$$

Starting from a temperature  $T_{hot}(t = t_0) = T_0$ , the hot block cools according to

$$\dot{T}_{hot}(t) = \frac{\kappa}{mc} (T_0 - T_{hot}(t))$$

**Laboratory procedure:**

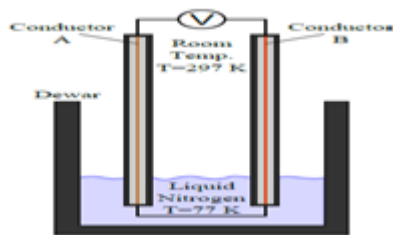
**Measurements with the thermocouples**

Three metallic conductors are supplied in the lab: 1) phosphorbronze, 2) copper, and 3) constantan. Each conductor is contained inside a stainless steel tube with BNC connections at both ends. The Seebeck coefficients for these materials are

not very large. Therefore, liquid nitrogen (LN2) Dewar is supplied to provide a large temperature difference between LN2 at TLN ' 77K and room temperature (TRT ' 297 K). The supplied thermometer can be used to monitor the room temperature ends of the tubes, but TLN does not need to be measured. See Fig 7 for a schematic of the measurement.

Thermocouple measurement procedure:

- 1 Measure and record the room temperature resistance of each conductor individually
- 2 Combine the conductors together in pairs and measure the three thermo voltages using the LN2 Dewar
- 3 Determine the three effective Seebeck coefficients:
  - (a) SC-Cu for constantan and copper
  - (b) SPB-Cu for phosphor-bronze and copper
  - (c) SC-PB for constantan and phosphor-bronze

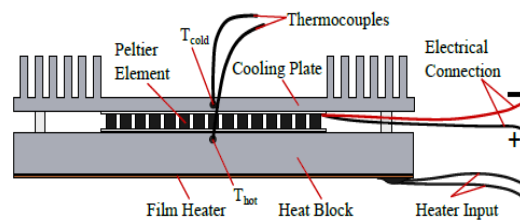


#### MEASUREMENT OF THERMOCOUPLES

The two conductors, A and B, are enclosed inside two stainless steel tubes. They are connected together at one end and submerged in LN2 Dewar to cool them to TLN ' 77 K. The other ends remain at room temperature (TRT ' 297 K), and the voltage difference between the conductors is measured with a voltmeter.

#### Measurements with the Peltier device:

The Peltier setup in the lab consists of a commercial Peltier device placed between two aluminum heat reservoirs as shown in Fig 8. The "hot" reservoir is an aluminum block covered with thermal insulation. The "cold" reservoir is an aluminum block machined with cooling fins. A fan can be placed on the cold reservoir to improve its cooling power. This is recommended because it helps stabilize the temperature gradient.



#### MEASUREMENT WITH PELTIER DEVICE

A schematic diagram of the Peltier laboratory setup. The Peltier device is mounted between two aluminum masses. The bottom heat block can be heated with the film heater by applying a current to the heater inputs. The cooling plate on top can be cooled with the fan (not shown). The dual channel thermometer probes (thermocouples) are inserted into two holes for measuring the temperature difference.

$$\Delta T = T_{\text{hot}} - T_{\text{cold}}$$

The electrical connections of the Peltier device are used to apply and measure voltage and current.

#### Warm-up procedure:

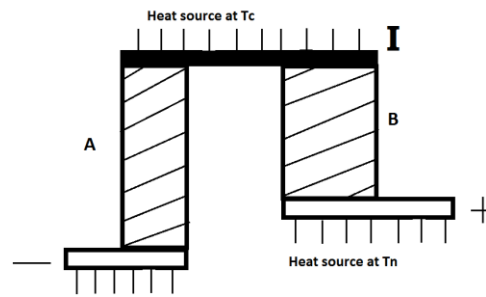
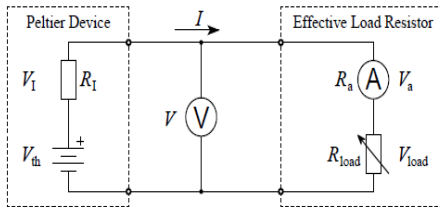
Before you start, get everything ready to record time-dependent data. Ideally you will record  $T_{\text{cold}}$ ,  $T_{\text{hot}}$ , and  $V_{\text{th}}$  simultaneously. This is done best by heating slowly so that values do not change rapidly. You will measure with the two thermocouples embedded in the Al masses. Digital multi-meters are available to measure electrical properties. The thermometer and the multi-meters have a "hold" feature for pausing the measurements. This can help when recording time-dependent data.

1. Connect the thermometer probes and a voltmeter to the electrical connections of the Peltier device.
2. Place the fan on the cold block and turn it on.
3. Apply 12V to the heater film. About 1A of current will flow.
4. Measure  $T_{\text{cold}}$ ,  $T_{\text{hot}}$ , and  $V_{\text{th}}$  as the system heats up.
5. It can take 30 min before the temperatures stabilize.

#### Constant temperature measurements:

1. While waiting for the temperatures to stabilize, measure all the resistor values,  $R_{\text{load}}$ , in the circuit box and measure,  $R_a$ , the resistance of the ammeter.
2. Make sure the voltmeter spans both the load resistor and the ammeter.
3. Once the temperatures have stabilized, record  $\Delta T$ .
4. Measure  $V$  and  $I$  as a function of all  $R_{\text{load}}$  values.
5. Measure  $V$  and  $I$  when  $R_{\text{load}} = 0$ , that is, only use  $R_a$ .

6. Measure  $V = V_{th}$  at  $I = 0$ , that is,  $V$  when  $R_{load} = 1$
7. Measure  $\Delta T$  again to see if there was a temperature drift



**PELTIER DEVICE DATA ANALYSIS**

**CONSTANT TEMPERATURE MEASUREMENT**

The circuit diagram for a Peltier device when connected to an electrical load. In addition to the internal resistance of the Peltier device,  $R_I$ , the setup includes a variable load resistance,  $R_{load}$ , and the resistance of the ammeter  $R_a$ . The temperature gradient generates the internal thermo voltage,  $V_{th}$ . Voltages  $V_I$ ,  $V_a$ , and  $V_{load}$  are created across resistances,  $R_I$ ,  $R_a$ , and  $R_{load}$ , respectively. An ammeter is used to measure the current,  $I$ . A voltmeter is used to measure the voltage drop,  $V$ , across the total effective load resistance,  $R_a + R_{load}$ .

**Cool-down procedure:**

While the system cools down, you will measure the thermal conductance

1. Return the system to the open-circuit condition used during the warm-up procedure. That is, disconnect the ammeter and use only the volt-meter
2. Get ready to measure time-dependent data
3. Disconnect the heater and start recording  $T_{cold}$ ,  $T_{hot}$ , and  $V_{th}$  as the system cools down. This can take more than 20 minutes

**Data analysis:**

In your lab report you should discuss your results as well as observations that you deem relevant. Your data should be presented in an appropriate manner {that is, analyze your raw data and present it in an informative way. State and justify your assumptions. In addition, address following points (which will help you to analyze your data)

**Peltier device data analysis:**

1. Heat absorption and heat rejection occur only at the junctions
2. Thermal conductivity and electrical resistance are constant over the range of temperature under consideration
3. Thomson coefficient is negligible

Net refrigerating effect at the junction is given by

$$Q_1 = \alpha_{ab} T_c - 1/2 I^2 R - U(T_h - T_c)$$

Where  $Q_1$  = Net refrigeration effect at the cold junction

$P_{\alpha_{ab}}$  = Relative seebeck coefficient for material A and B

Heat source at  $T_c$

$I$  = current in amps

$R$  = Total electric resistance of the circuit in ohms

$$= L_a / A_a \sigma_a + L_b / A_b \sigma_b$$

$U$  = Total thermal conductance of branches in parallel

$$= A_a K_a / L_a + A_b K_b / L_b$$

$T_c$  and  $T_h$  = temperature of hot and cold junctions respectively in Kelvin

$\sigma$  = Electrical conductivity and

$K$  = Thermal conductivity

$A_a$  and  $A_b$  = constant cross-section areas of two branches

$L_a$  and  $L_b$  = Lengths of two branches

$\Phi$  = Refrigerating effect/Power- input

**CHARACTERISTIC VALUES OF A PELTIER COOLER**

**Power supply**

- **Voltage**

Basically the cooling capacity depends on the current. The cooling units are usually built for using at constant dc voltage e.g. 12V, 24V. We advise you to reduce the maximum ripple to 10%, preferably to 5% for an optimal operation. If the voltage rises over the nominal value, the increase of the cooling performance is small or even declines and the efficiency drops intense.



If the voltage is reduced, the maximum temperature difference cannot be achieved any more. The cooling power reduces in equal measure, but the COP rises. The use of adjustable DC supplies makes a rough adjustment for the temperature possible. If an exact temperature is required, a controller must be used.

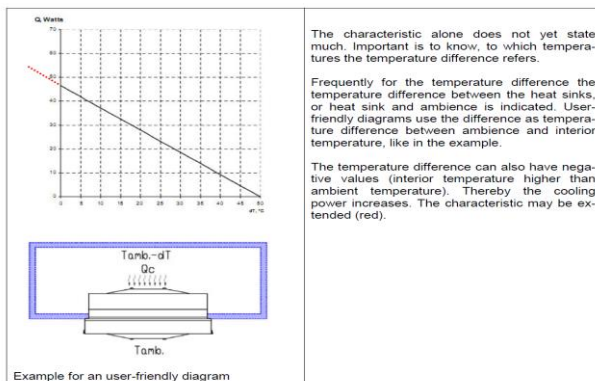
Please note that the fans have always to be operated with rated voltage. By reversal of the polarity one heats instead of cools. So the cooling unit can be used as air conditioner. Please note that the polarity of the fans may not be inverted (=> separate supply)

• **Current**

The initial current is larger than the current in continuous operation. Consider this for the dimension of the power supply. With increasing temperature difference at the cooling unit the current decreases.

**Relation between temperature difference and cooling power**

Data such as 300W cooling unit, maximal cooling power 250W, operating cooling power 180W say little about the efficiency of a cooling unit. The cooling performance depends on the temperature difference. Please see in the following diagram.

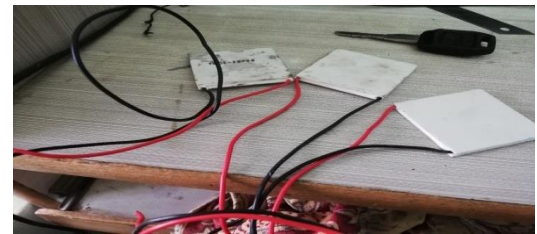


**III COMPONENTS USED FOR COOLING**

1. Peltier Cells
2. Radiators
3. Designing of copper box
4. Battery
5. Thermometer
6. Water pumps

**Peltier Cells:**

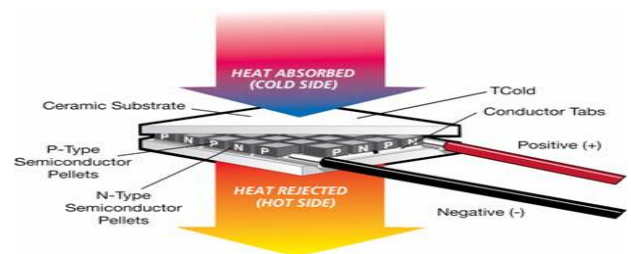
The project is entirely depends on peltier effect. So, The cooling process we attain more by arranging 2 peltier in our project. The two peltiers works on 12V and 6 amps each. peltier exhibit semiconductor properties.



PELTIER CELL

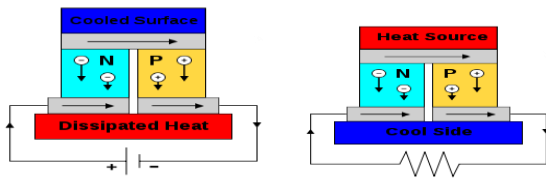
If a piece of solid is heated at one end, the charge carried (electron in metals) will leave this region and move to the cooler part. The density of the electrons at the cooler end increases and an equilibrium condition is reached as the negatively charged region opposes a further flow of electrons from the hot end. Thus, a potential is developed across the two ends of the material.

The magnitude of this thermo emf, (Seebeck) is dependent on the number of charge carriers. The smaller the number of carriers, the large is Seebeck voltage. In semiconductors, the number of charge carriers is very much smaller (about  $10^4$  to  $10^{18}/\text{cm}^3$ ) compared to that in metal (about  $10^{22}/\text{cm}^3$ ). The Seebeck coefficient of a semiconductor is about  $200\mu\text{volts}/^\circ\text{C}$  while that of metal is only of the order of a few micro volts. The current is considered as the flow of negatively charged particles (electrons). The conventional direction of current flow is usually taken opposite to the flow of electrons.



**CONVECTIONAL DIRECTION OF CURRENT FLOW**

Semiconductor materials generally exhibit very large thermoelectric emf. As compared to the metals, Both Ntype and Ptype semiconductors can be used. N type semiconductor is one where current carriers are mostly electrons. If such a semiconductor is sandwiched between two metal strip and connected to D C voltage source as shown in fig(a) the junction where the current enters becomes hotter and other junction gets cooler.



**PELTIER CELL DIODE FLOW**

Current conduction can also take place due to the flow of positive charges (holes) as in Ptype semiconductor as shown in fig. In this case, the effect is opposite to that observed in Ntype semiconductor. Coupling Ntype and Ptype semiconductors as shown in fig will produce maximum cooling effect. The temperature the cold end can be lowered below the room temperature if the heat liberated at hot end be dissipated continuously.

**RADIATORS:**

Radiators are simple heat exchangers which distribute the heat by natural air circulation (very little heat is transferred through radiation despite the name). 80 or so years ago most radiators were made from cast iron, now they are mostly made from pressed steel; a few are made from aluminum.

Manufacturers all produce data sheets showing the output of their radiators and many software companies (and radiator manufacturers) produce simple software so you can calculate radiator size. Normally manufacturers' data sheets will quote radiator output when there is a temperature difference (water to air) of 50 °C. Where the temperature differs from this, correcting factors are necessary to determine actual output and therefore size. So, for instance, if a radiator is required which will run at a lower temperature than normal, its size must be increased to compensate. Radiators can be single panel or double panel and with, or without, fins (right). Doubling up the radiators and adding fins increases output without increasing the amount of space taken up by the radiator.

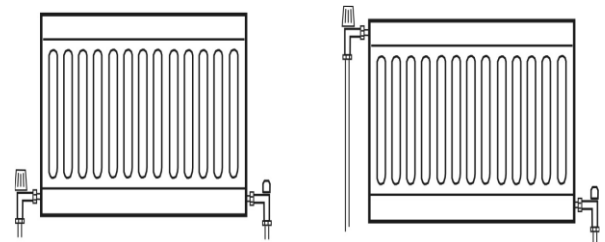


**RADIATOR**

**One pipe and two pipe systems:**

Many of the earlier pumped systems used what is known as a one-pipe system. Water flows from radiator to radiator and then back to the boiler. However, as the water flows into each radiator, heat is drawn from it and therefore the water, which reenters the flow pipe, is slightly cooler. Indeed, towards the end of the run the radiators are significantly cooler. This can be overcome to a certain extent by progressively increasing the size of the radiators; this is expensive and looks rather odd.

In a two-pipe system there are two pipe circuits, one a flow pipe and the other a return: each radiator is connected to both. The water, which leaves the radiator, flows into a return pipe, which goes back to the boiler. The same process occurs in all the other radiators. Therefore, all of the radiators receive water at more or less the same temperature.



**TYPES OF RADIATORS**

Radiators need to be balanced to make sure they are all roughly at the same temperature (before any control is exercised via thermostatic radiator valves). There is a problem, otherwise, of radiators near to the boiler getting quite hot and radiators further away staying cool. To avoid this, the outlet of each radiator is fitted with a 'lock shield valve' which needs to be adjusted when the system is first installed. Balancing the rods evens out the flow of water through each radiator so that when the central heating system is working normally, the temperature drop across each radiator is about 12°C. Balancing procedure is beyond the scope of this article but it usually involves checking the incoming and outgoing water temperature at each radiator.

Adjustments can be made by tightening or loosening the lock shield valve; this controls the water flowing through the radiator. Once the radiators have been balanced, no further adjustment should be required until the boiler is renewed or radiators are changed.

**Radiator sizing**

The heat output of the radiators should be carefully calculated. Radiators should, where possible, be sited under

windows to counteract cold downdraughts and to give a more comfortable environment in the room. Radiators should be installed close to the floor, preferably 100&150mm above finished floor level. Wide, low radiators will be more effective at heating the room evenly than tall, narrow ones. Enclosures around radiators reduce the heat output but might be required to prevent vulnerable people getting burnt.

The heat loss calculation is normally done on a room by room basis to work out radiator sizes. For each room the heat loss through each construction element is established. The heat loss is the 'area x 'U' value x temperature difference inside and outside' (standard values are normally used see table). In addition allowance has to be made for heating the air due to air changes. Note that in some rooms there will be a flow of heat INTO the room. When the heat loss has been calculated a correction factor is normally applied when sizing the radiator.

For example, if a condensing boiler is being used and the radiators are running fairly cool (to ensure the water in the return pipe will condense in the boiler) the correction factor may be as high as 50%. In this case the radiator will have to have an output of nearly 1200watts. Adding together the total heat loss (in all the rooms) helps size the boiler.

### Design of copper box

Copper alloys are prime candidates for high heat flux applications in fusion energy systems. High heat flux is a major challenge for various fusion devices because of the extremely high energy density required in controlled thermonuclear fusion. The removal of a large amount of heat generated in the plasma through the first wall structure imposes a major constraint on the component design life.

Materials with high conductivity are needed to assist heat transfer to the Coolant and to reduce the thermal stress for pulsed mode of operation. A number of issues must be considered in the selection of materials for high heat flux applications in fusion reactors. While high conductivity is the key property for such applications, high strength and radiation resistance are also essential for the effective performance of materials in a high heat flux, high irradiation environment. In addition, fatigue behavior is a major concern for many high heat flux applications because of planned or inadvertent changes in the thermal loading. Pure copper has high thermal conductivity but rather low strength, and therefore its application as heat sinks is limited.

The strength of copper can be improved by various strengthening mechanisms. Among them, precipitation

hardening and dispersion strengthening are the two most viable mechanisms for improving the strength of copper while retaining its high electrical and thermal conductivities. A number of precipitation hardened (PH) and dispersion strengthened (DS) copper alloys are commercially available, and have been evaluated for fusion applications, for example, PH CuCrZr, CuNiBe, CuNiSi.



DESIGN OF COPPER BOX

### Physical Properties of copper

Copper, atomic number 29 with an atomic weight of 63.54, exhibits a face centered cubic crystal structure. Copper is a transitional element and, being a noble metal, it has inherent properties similar to those of silver and gold. Its excellent conductivity, malleability, corrosion resistance and bio functionality stem from copper's elemental origins.

Copper has a high solubility for other elements such as nickel, zinc, tin and aluminum. This solid solution  $\alpha$  phase is responsible for the high ductility exhibited by copper alloys. Alloying additions beyond the solubility limit result in the  $\beta$  phase, which exhibits a body centered cubic (bcc) structure. This  $\beta$  phase has high temperature stability, and alloys that exhibit an  $\alpha+\beta$  structure have excellent hot forming capability. The density of copper is 0.321 lb/in<sup>3</sup> (8.96 g/cc), and its melting point is 1981°F (1083°C). All of these properties and characteristics are significantly modified when copper is alloyed.

**Electrical & Thermal Conductivity:** Conductivity is the primary characteristic that distinguishes copper from other metals. The electrical conductivity of materials is measured against that of a standard bar of "pure" copper that in 1913 was assigned a value of 100% IACS (International Annealed Copper Standard). Since that time, improved processing techniques and higher purity ingots have resulted in commercial copper with electrical conductivity values slightly above 100% IACS.

The thermal and mechanical processing variations used to produce commercial alloys can cause profound changes in their conductivity, and frequently the alloys with the highest strengths have the lowest conductivity. The IACS

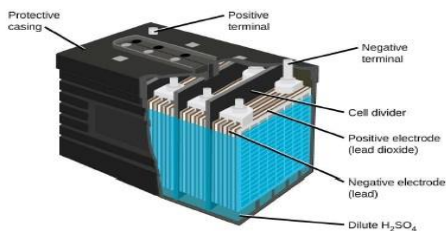
values are usually published as minimum values for annealed tempers Tempered (cold worked) products may have a value 1 to 5 percentage points below the annealed value

Alloys of higher electrical resistivity (R) will waste more energy, since heat generated due to an electric current (I) is proportional to  $I^2$  times the resistance The heat generated will increase the temperature of the component, with potentially adverse consequences Higher thermal conductivity alloys allow the designer to dissipate some of that heat, minimizing any temperature rise Within alloy families, thermal conductivity tends to be related to electrical conductivity; *i e* , alloys of higher electrical conductivity will tend to have higher thermal conductivity

This rule of thumb is convenient since thermal conductivity is rather difficult to measure, while electrical conductivity, or its inverse, electrical resistivity, is easy to measure The nearly linear relationship between thermal and electrical conductivity at 68°F (20°C) for selected copper alloys

## BATTERY:

**Definition:** devices that transform chemical energy into electricity Every battery has two terminals: the positive cathode (+) and the negative anode (There are two types of batteries they are primary and secondary cells



BATTERY

## Primary and Secondary Batteries:

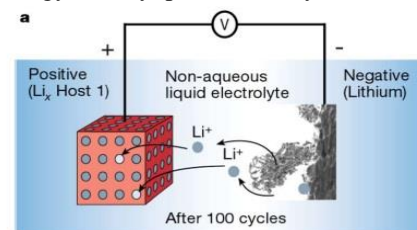
Primary batteries are disposable because their electrochemical reaction cannot be reversed Secondary batteries are rechargeable, because their electrochemical reaction can be reversed by applying a certain voltage to the battery in the opposite direction of the discharge



TYPES OF BATTERIES

## Standard modern batteries:

- **Zinc Carbon:** used in all inexpensive AA, C and D dry cell batteries The electrodes are zinc and carbon, with an acidic paste between them that serves as the electrolyte (Disposable)
- **Alkaline:** used in common Duracell and Energizer batteries, the electrodes are zinc and manganese-oxide, with an alkaline electrolyte (disposable)
- **Lead-Acid:** used in cars, the electrodes are lead and lead oxide, with an acidic electrolyte (rechargeable)
- **Nickel-cadmium:** (NiCd) rechargeable, “memory effect” Nickel-metal hydride: (NiMH) rechargeable, “memory effect” (less susceptible than NiCd)
- **Lithium-Ion:** (Li-Ion) rechargeable, no “memory effect”, high energy density, power rate, cycle life, costly



## TECHNICAL TERMS:

- **Energy Density:** Total amount of energy that can be stored per unit mass or volume How long will your laptop run before it must be recharged
- **Power Density:** Maximum rate of energy discharge per unit mass or volume Low power
- **Safety:** At high temperatures, certain battery components will breakdown and can undergo exothermic reactions
- **Life:** Stability of energy density and power density with repeated cycling is needed for the long life required in many applications
- **Cost:** Must compete with other energy storage technologies



BATTERY USED IN PROJECT (12v)

## THERMOMETER:

A thermometer is a device that measures temperature or a temperature gradient using a variety of different principles A thermometer has two important elements: the temperature

sensor (e.g. the bulb on a mercury-in-glass thermometer) in which some physical change occurs with temperature, plus some means of converting this physical change into a numerical value (e.g. the visible scale that is marked on a mercury-in-glass thermometer)



DIGITAL THERMOMETER

#### Types of thermometers:

- 1 contact-type thermometers
  - platinum resistance thermometer
  - liquid-in-glass thermometer
  - thermocouple
- 2 Radiation thermometers

#### WATER PUMP:

In This project we are using two water pumps

- The first water pump is used to pump water from radiator to tank and
- The second is used to circulate the entire jacket to copper box

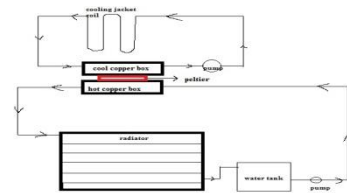


WATER PUMP

- Water pump is used to pump the water in two boxes for cooling and heating
- One of the copper box is attached to the cool side of the peltier cell and another one is attached to the heating side at water tank

#### IV. EXPERIMENTAL SETUP & ANALYSIS

##### BLOCK DIAGRAM OF EXPERIMENTAL SETUP:



##### CONNECTIONS ON HOT SIDE:

On the hot side of the peltier cell, a copper box is placed to receive the heat from the hot junctions of peltier. The water is used as a coolant to the hot side. The water absorbs the heat from conduction and convection process. It carries the heat away from hot box to radiator, where it gets cooled and it is collected in water tank. It again recirculates.

The fins provided to the radiator, increase the rate of heat transfer. The rate of Heat transfer from hot water to surroundings, when riding a bike. The rate of cooling of Hot water increases the rate of cooling on cold side.

##### CONNECTIONS OF COLD SIDE

On the cold side of the peltier, an insulated copper box is placed. It receives the cooling from the cold side of the peltier and transfers it to the flowing water. The water is circulated around the body for the riders and kept the body cool and protects the rider from de-hydration.

The rate of cooling depends upon the rate of cooling on the hot side of the peltier and the atmospheric temperature. The rate of heat dissipation increases on hot side, increases the rate of cooling. We can obtain 15 to 20°C within 20 minutes.

Thermoelectric cooling is not very efficient. It is often only about 10 percent efficient, compared to normal refrigeration, which is in the 40 to 60 percent range. Normal refrigeration isn't practical for a cooler, since it is heavy, bulky and overpowered. But the thermoelectric cooler doesn't have to do that much.

The refrigerator is insulated, so not much heat leaks in. It is also quite small, so it takes much less energy to cool than a refrigerator.

The efficiency of a thermoelectric cooling unit is indicated as the COP (Coefficient of Performance). It is defined as follows:

$$COP = \frac{Q_c}{P_{el}}$$

$Q_c$ : cooling power  
 $P_{el}$ : electrical power

The COP depends on the temperature difference. The higher the temperature difference, the smaller is the COP.

**OPERATING TEMPERATURE RANGE:**

The operating temperature range of a cooling unit is determined by the thermoelectric modules and the fans. There are thermoelectric modules for operating temperatures up to 200°C. At low temperatures, the cooling power decreases strongly due to the material.

**INGRESS PROTECTION (IPX):**

The reachable ingress protection depends on the fans. They are exposed to the environment. Fans are available with ingress protection IP67. The thermoelectric modules can be sealed. The cooling units can be developed in such a way that no water or humidity enters the cooling unit. Standard cooling units meet IP54.

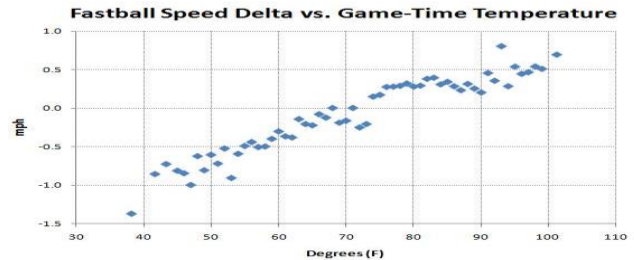
**RELIABILITY**

Thermoelectric cooling units are considered, construction based, as very reliable. With inappropriate treatment, the following errors can occur:

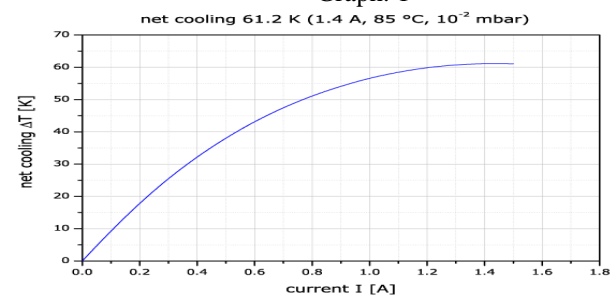
- Overheating of the thermoelectric module because of insufficient heat dissipation (heat sink, fan) on the hot side or too high voltage
- Quick or large changes of temperature on the hot and/or cold side. One may not exceed the maximum operating temperature, defined in the specifications, in every case. An excess of the maximum temperature leads to a decrease of cooling power or even to a loss. The temperature range can be extended by the choice of suitable thermoelectric modules.

If a cooling unit is used in the cycling mode, (heating / cooling), special thermoelectric modules should be used. They withstand temperature depending mechanical stress in the cycling mode. Compared to standard thermoelectric modules, they withstand more cycles under same conditions. The MTBF (Mean Time between Failures) for thermoelectric modules of Kryotherm is 200'000 hours at ambient temperature. The life cycle of the fans is shorter and thus crucial. Thermoelectric cooling is not very efficient. It is often only about 10 percent efficient, compared to normal

refrigeration, which is in the 40 to 60 percent range. Normal refrigeration isn't practical for a cooler, since it is heavy, bulky and overpowered. But the thermoelectric cooler doesn't have to do that much. The refrigerator is insulated, so not much heat leaks in. It is also quite small, so it takes much less energy to cool than a refrigerator.

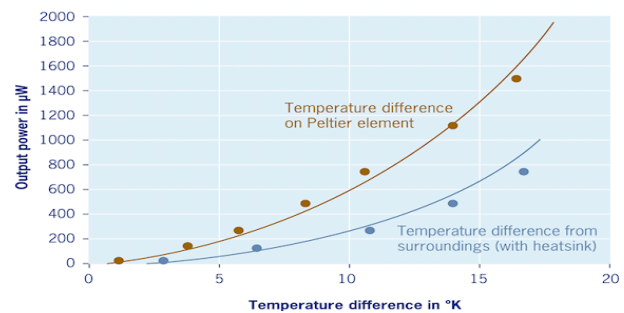


Graph: 1



Graph: 2

~ 100 μW energy produced for 7 K temperature difference



Graph-3

**Applications:**

- In a typical small domestic refrigerator, a cooling power of about 50 watts is required. In principle, this can be provided by a single thermocouple. However, a very large current (1000amps) is required at a very low D C voltage (0.1 V). In order to limit this current to a reasonable value, it is necessary to increase the number of couples. This will also step up the applied D C voltage to a few volts, which can be easily obtained. A typical form of construction of a practical thermoelectric refrigerator is shown below. In spite of certain practical difficulties, such as availability of high current, low voltage D C current source, peltier refrigerators are gaining

prominence and are now widely used in several western countries. These refrigerators in very compact form on a moving trolley are used in some international airlines to provide cold drinks and hot snacks as it can be used for heating and cooling also just by changing the terminal knob of the refrigerators

- Peltier cooling can also be made use of in air-conditioning of rooms where large cooling capacities are required but the temperature differences need not be so large. The cooling unit can form part of one of the walls and heat appearing at the outside face of the unit can be radiated to the surrounding air by means of suitable fins. The great advantage of this system is that it can be used for heating the room in winter merely by reversing the direction of current. Such a heating is more effective than would be the case if the current is passed through ordinary resistance heater wires because in this case, the system acts as a heat pump.
- Apart from these domestic applications, thermoelectric cooling can be effectively used in a number of scientific and applications. To name a few, the applications include constant low temperature bath and chambers, cooled baffles for oil diffusion pump in vacuum systems, dew point hygrometer for determining absolute humidity, photomultiplier cooler, cooling the biological tissues for facilitation of slicing thin sections, serum coolers for preservation of blood plasma and serums and many others.

#### ADVANTAGES:

1. Simple and less number of parts is required
2. Thermo-electric units are much more flexible than conventional units
3. It can take overload simply by increasing power input
4. These units being static are more reliable than rotating or reciprocating equipments
5. These units are noiseless and there are no moving parts
6. Control is easy as it is done merely by adjusting the current supply
7. Very compact in size and suitable for low capacity
8. It can operate in any position
9. Infinite life is expected
10. The weight per unit refrigeration is considerably lower than conventional refrigeration systems
11. No leakage problem
12. Just by reversing the polarity results in an inter change of heating and cooling process
13. An important advantage of thermo electric refrigeration is the independence of C O P on the size of thermo electric refrigerator and this makes it

particularly attractive to use Peltier cooling when cooling capacity is required is high

14. Peltier cooling can also be used in air conditioning rooms where large cooling is required but the temperature difference is small. The large cooling unit can form a part of the inside walls and the outside face of the unit can be exposed to the surrounding air by means of suitable films
- A great advantage of such thermo electric conditioning system is that, it can be used for heating the room in winter merely by reversing the direction of current. Such as heating is more effective than would be the case if current is passed through ordinary resistance heater wires because in this case, the system acts as a heat pump
  - **Solid state design**
    1. No moving parts
    2. Integrated chip design
    3. No hazardous gases
    4. Silent operation
  - **Compact and lightweight**
    1. Low profile
    2. Sizes to match your component footprint
    3. No bulky compressor units
    4. Perfect for bench top applications
  - **High reliability**
    1. 100,000 hours + MTBF
  - **Precise temperature stability**
    1. Tolerances of better than +/- 0.1°C
    2. Accurate and reproducible ramp and dwell times
  - **Cooling/heating mode options**
    1. Fully reversible with switch in polarity
    2. Supports rapid temperature cycling
  - **Localized Cooling**
    1. Spot cooling for components or medical applications
    2. Perfect for temperature calibration in precision detection systems

- **Rapid response times**

1. Instantaneous temperature change
2. Reduced power consumption

- **Low DC voltage designs**

- **Dehumidification**

1. Efficient condensation of atmospheric water vapor

## V CONCLUSION AND FUTURE SCOPE

The objective of the project is to achieve the cooling for the rider when riding in hot weather as well as we can acquire heating effect while cooling in cool weather. A peltier Cooling system is has been designed and developed to provide active cooling with help of single stage 12 V TE module to provide adequate cooling. First the cooling load calculations for this peltier component considered under study were presented. Simulation tests in laboratory have validated the theoretical design parameters and established the feasibility of providing cooling with single stage thermoelectric cooler was tested in the environmental chamber.

As peltier cell not available in open market, which we can retain cooling at case of power outage due to high current carrying capacity. The retention time achieved was 52 min with the designed module in this project. In order to achieve the higher retention time, another alternative was incorporate. This consists the additional heater on heat sink. The highest retention time achieved was 57 minutes S.

### Future Scope

With recent development taking place in field of thermoelectric and nano science different thermoelectric material with figure of merit ZT more than one with high temperature difference to be explored this will further help to reduce the temperature, current below and can also perform better at higher ambient conditions. To improve the power retention in this thermoelectric cooler sandwich heater needs to be explored with quick switching mechanism from thermoelectric cell off state of heater to on state, so that temperature drop in thermoelectric cell can be reduced.

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